Product Change Notification: DSNO-27MYTN998

Date:

30-Sep-2026

Product Category:

Automotive LED Drivers, General Purpose LED Drivers

Notification Subject:

CCB 7630.001 Initial Notice: Qualification of Double Ring Ag as new lead-frame DAP surface prep material for AT9919K7-GVAO, HV9918K7-G, HV9919BK7-G, AT9919K7-G and HV9967BK7-G catalog part numbers (CPN) available in 8L WDFN (3x3x0.8mm) package at ATP7 assembly site.

Affected CPNs:

DSNO-27MYTN998_Affected_CPN_09302026.pdf
DSNO-27MYTN998_Affected_CPN_09302026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of Double Ring Ag as new lead-frame DAP surface prep material for AT9919K7-GVAO, HV9918K7-G, HV9919BK7-G, AT9919K7-G and HV9967BK7-G catalog part numbers (CPN) available in 8L WDFN (3x3x0.8mm) package at ATP7 assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)
Assembly Site	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	No
Wire Material	Au	Au	No

Die Attach Material	AP4300 (PFAS-free)	AP4300 (PFAS-free)	No
Molding Compound Material	G631BQF	G631BQF	No
Lead-Frame Material	C194	C194	No
DAP Surface Prep	Ring Ag	Double Ring Ag	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on time delivery performance by qualifying Double Ring Ag as a new lead frame DAP surface prep material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: December 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	September 2026					>	**December 2026**				
Work Week	36	37	38	39	40		45	46	47	48	49
Initial PCN Issue Date					x						
Qual Report Availability											x
Final PCN Issue Date											x

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan. This is a qualification by similarity (QBS) to CCB#7630.

Revision History: September 30, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-27MYTN998_Qual_Plan_CCB7630.pdf
PCN_DSNO-27MYTN998_Pre and Post Change Summary.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

DSNO-27MYTN998 - CCB 7630.001 Initial Notice: Qualification of Double Ring Ag as new lead-frame DAP surface prep material for AT9919K7-GVAO, HV9918K7-G, HV9919BK7-G, AT9919K7-G and HV9967BK7-G catalog part numbers (CPN) available in 8L WDFN (3x3x0.8mm) package at ATP7 assembly site.

Affected Catalog Part Numbers (CPN):

AT9919K7-GVAO

HV9918K7-G

HV9919BK7-G

AT9919K7-G

HV9967BK7-G

QUALIFICATION PLAN SUMMARY

PCN #: DSNO-27MYTN998

Date:
May 22, 2025

Qualification of Double Ring Ag as new lead-frame DAP surface prep material for AT9919K7-GVAO, HV9918K7-G, HV9919BK7-G, AT9919K7-G and HV9967BK7-G catalog part numbers (CPN) available in 8L WDFN (3x3x0.8mm) package at ATP7 assembly site. This is a Q100 Grade 1 qualification.

Purpose: **Qualification of Double Ring Ag as new lead-frame DAP surface prep material for AT9919K7-GVAO, HV9918K7-G, HV9919BK7-G, AT9919K7-G and HV9967BK7-G catalog part numbers (CPN) available in 8L WDFN (3x3x0.8mm) package at ATP7 assembly site.**

CCB No.: **7630**

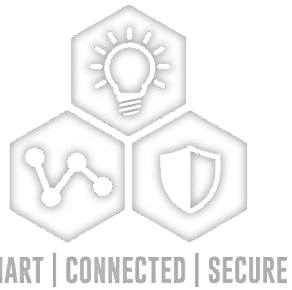
Misc.	Assembly site	ATP7
	BD Number	TBD
	MP Code (MPC)	VAGAxxxx VAKA1xxx
	Part Number (CPN)	Various
	MSL information	MSL-1, 260'C
	Assembly Shipping Media (T/R, Tube/Tray)	Cannister
	Base Quantity Multiple (BQM)	3,300
	Reliability Site	MTAI
Lead-Frame	Paddle size	106X75
	Material	C194
	DAP Surface Prep	Ring Ag
	Treatment	Rough
	Process	Etch
	Lead-lock	Yes (Half Etch)
	Part Number	101431257
	Lead Plating	Matte Sn
	Strip Size	70x250mm
	Strip Density	1224
Bond Wire	Material	Au
Die Attach	Part Number	AP4300
	Conductive	Yes
MC	Part Number	G631BQF
PKG	Package Type	WDFN
	Pin/Ball Count	8
	PKG width/size	3x3x0.8mm

Test Name	Conditions	Reliability Stress Read Point Grade 1: -40°C to +125°C (MCHP E Temp)	Pre & Post Reliability Stress Test Temperature Grade 1: -40°C to +125°C (MCHP E Temp)	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Pkg. Type	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hours of steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.			22	5	1	27	>95% lead coverage	5	MTAI	MTAI	WDFN	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Backward Solderability	J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hr steam aging for NiPdAu finish prior to testing. Backward: Matte tin/ NiPdAu finish, SnPb solder, wetting temp 215°C for SMD.			22	5	1	27	>95% lead coverage	5	MTAI	MTAI	WDFN	
Wire Bond Pull - WBP	Mil. Std. 883-2011			5	0	1	5	0 fails after TC	5	ATP7	ATP7	WDFN	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001			5	0	1	5	0	5	ATP7	ATP7	WDFN	30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108			10	0	3	30	0	5	ATP7	ATP7	WDFN	
External Visual	Mil. Std. 883-2009/2010			All devices prior to submission for qualification testing	0	3	ALL	0	5	MTAI	MTAI	WDFN	
HTSL (High Temp Storage Life)	JESD22-A103 +125°C, +150°C or +175°C	Grade 1: 500 hrs (+175°C) or 1000 hrs (150°C)	Grade 1: +25°C, +125°C	45	5	1	50	0	21 - 83	MTAI	MTAI	WDFN	Spares should be properly identified.
Preconditioning - Required for surface mount devices	J-STD-020 JESD22-A113 MSL-1, 260'C +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type.		Grade 1: +25°C	231	15	3	738	0	15	MTAI	MTAI	WDFN	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A101 or A110 +130°C/85% RH for 96 hrs or +110°C/85%RH for 264 hrs	Grade 1: 96 hrs (+130°C/85% RH) or 264 hrs (+110°C/85%RH)	Grade 1: +25°C, +125°C	77	5	3	246	0	10 - 14	MTAI	MTAI	WDFN	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A102, A118, or A101 +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs	Grade 1: 96 hrs (+130°C/85% RH) or 264 hrs (+110°C/85% RH)	Grade 1: +25°C	77	5	3	246	0	10	MTAI	MTAI	WDFN	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104 -55ºC to +125ºC, -55ºC to +150ºC	Grade 1: 1000 cycles (-55ºC to +150ºC)	Grade 1: +25°C, +125°C	77	5	3	246	0	15 - 60	MTAI	MTAI	WDFN	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

CCB 7630.001
Pre and Post Change Summary
PCN #: DSNO-27MYTN998

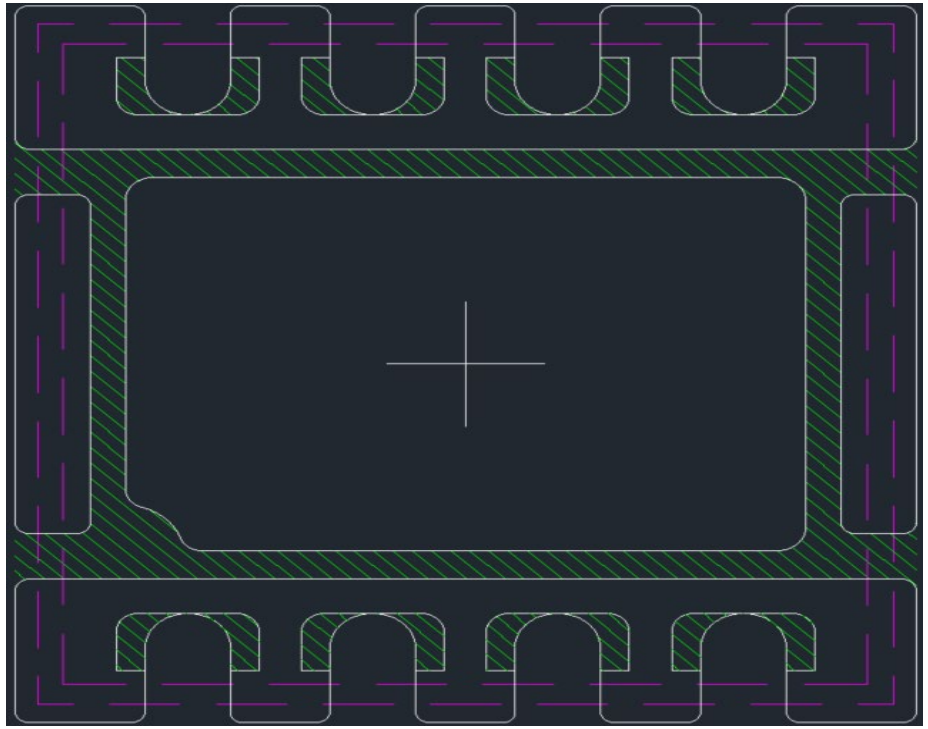


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Lead-Frame Comparison

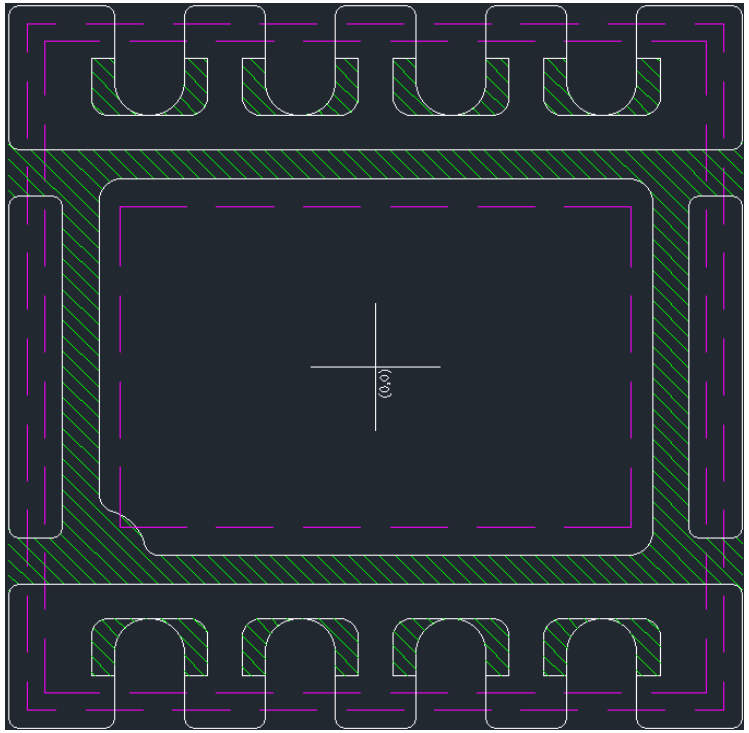
Pre Change



Note: Not-to-scale

DAP Surface Prep	Ring Ag

Post Change



Note: Not-to-scale

DAP Surface Prep	Double Ring Ag